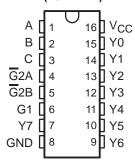
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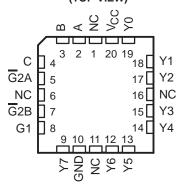
- Operating Voltage Range of 4.5 V to 5.5 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical  $t_{pd} = 17 \text{ ns}$
- ±4-mA Output Drive at 5 V

SN54HCT138...J OR W PACKAGE SN74HCT138...D, N, NS, OR PW PACKAGE (TOP VIEW)



- Low Input Current of 1 µA Max
- Inputs Are TTL-Voltage Compatible
- **Designed Specifically for High-Speed Memory Decoders and Data Transmission Systems**
- **Incorporate Three Enable Inputs to Simplify** Cascading and/or Data Reception

SN54HCT138...FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

The 'HCT138 devices are designed for high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

#### ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HCT138N	SN74HCT138N
		Tube of 40	SN74HCT138D	
	SOIC - D	Reel of 2500	SN74HCT138DR	HCT138
4000 1- 0500		Reel of 250	SN74HCT138DT	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HCT138NSR	HCT138
		Tube of 90	SN74HCT138PW	
	TSSOP - PW	Reel of 2000	SN74HCT138PWR	HT138
		Reel of 250	SN74HCT138PWT	
	CDIP – J	Tube of 25	SNJ54HCT138J	SNJ54HCT138J
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HCT138W	SNJ54HCT138W
	LCCC – FK Tube of 55		SNJ54HCT138FK	SNJ54HCT138FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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# SN54HCT138, SN74HCT138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

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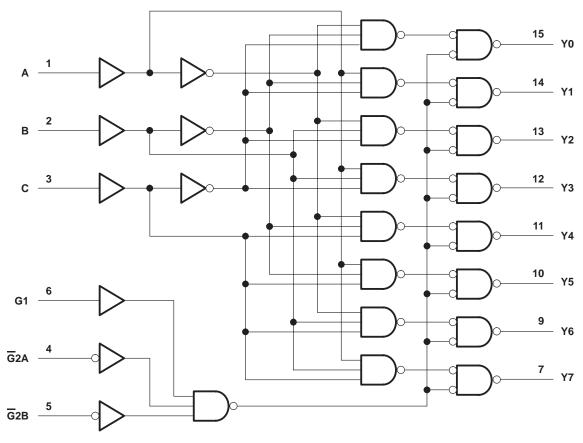
#### description/ordering information (continued)

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low  $(\overline{G})$  and one active-high (G) enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

#### **FUNCTION TABLE**

	INPUTS				OUTPUTS								
	ENABLE	Ē	:	SELEC1	<u> </u>				0011	010			
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Χ	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	X	Н	Χ	Χ	X	Н	Н	Н	Н	Н	Н	Н	Н
L	X	X	X	Χ	X	Н	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
Н	L	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
Н	L	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
Н	L	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
Н	L	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
Н	L	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
Н	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
Н	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L

#### logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V	to 7 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> ) (see Note 1	) ±	:20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see N	ote 1) ±	20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±	25 mA
Continuous current through V <sub>CC</sub> or GND		:50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	age 75	3°C/W
N packa	age 6°	7°C/W
NS pac	kage6	4°C/W
PW pag	kage 108	8°C/W
Storage temperature range, T <sub>stg</sub>		150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

# SN54HCT138, SN74HCT138 3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS

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#### recommended operating conditions (see Note 3)

				SN54HCT138			SN74HCT138		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2			2			V
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V			0.8			0.8	V
٧ <sub>I</sub>	Input voltage		0		VCC	0		Vcc	V
VO	Output voltage		0		VCC	0		Vcc	V
Δt/Δν	Input transition rise/fall time				500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		.,	T <sub>A</sub> = 25°C			SN54HCT138		SN74HCT138		
PARAMETER			vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
V	Mr. Mr. ander	I <sub>OH</sub> = -20 μA	45.1/	4.4	4.499		4.4		4.4		V
VOH	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
.,	$V_{I} = V_{IH} \text{ or } V_{IL} \qquad \frac{I_{OL} = 20  \mu\text{A}}{I_{OL} = 4 \text{ mA}} \qquad 4.5 \text{ V}$	4514		0.001	0.1		0.1		0.1		
V <sub>OL</sub>		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	V
lj	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	5.5 V			8		160		80	μΑ
Δl <sub>CC</sub> †	One input at 0.5 V Other inputs at 0 o		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or VCC.

## switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

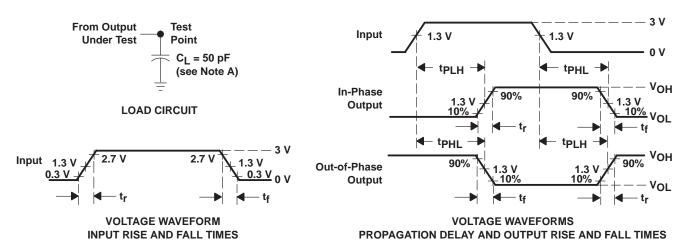
DARAMETER	FROM	то	,,	T,	λ = 25°C	;	SN54H	CT138	SN74H	CT138	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> pd	A D 0	Any Y	4.5 V		23	36		54		45	
	A, B, or C		5.5 V		17	32		49		34	ns
	Enable	Any Y	4.5 V		22	33		50		42	
			5.5 V		18	30		45		38	
t <sub>t</sub>			4.5 V		12	15		22		19	
		Ť	5.5 V		11	14		20		17	ns

#### operating characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	85	pF



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_r = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

#### 14 LEADS SHOWN

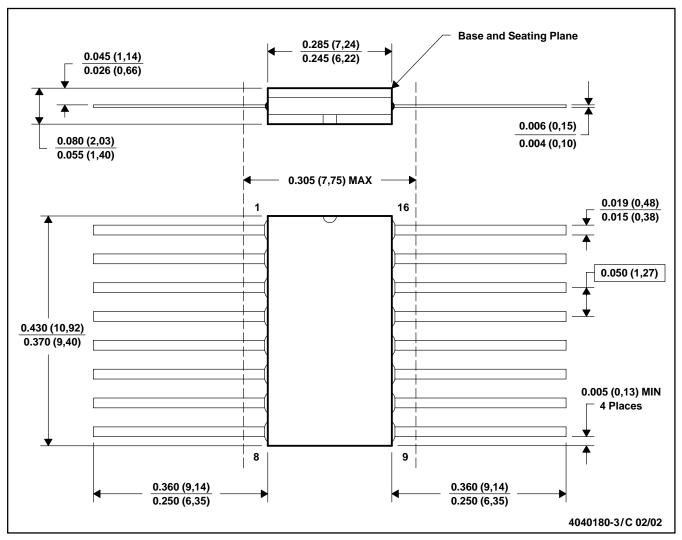


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

#### W (R-GDFP-F16)

#### **CERAMIC DUAL FLATPACK**



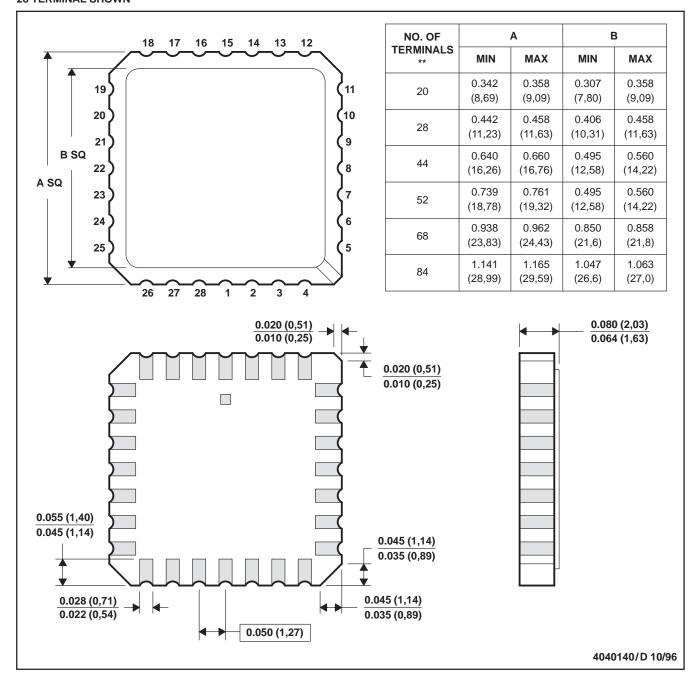
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP-1F16 and JEDEC MO-092AC

#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



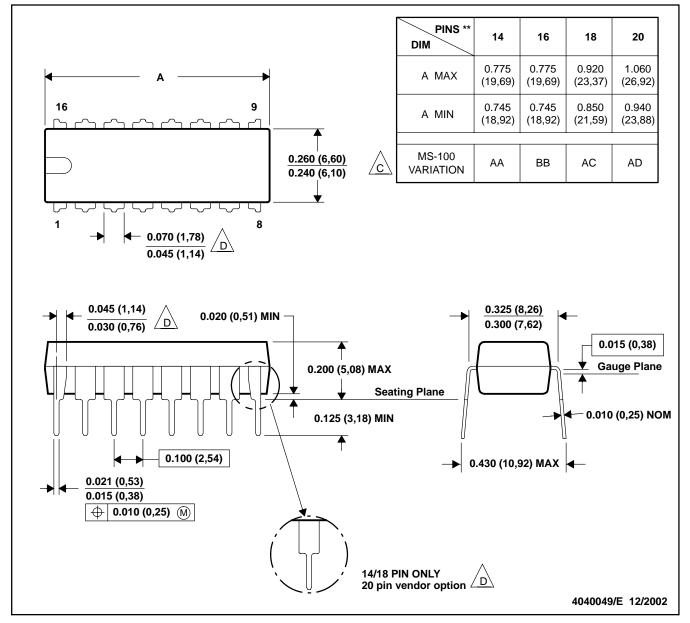
- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004



#### N (R-PDIP-T\*\*)

#### **16 PINS SHOWN**

#### PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

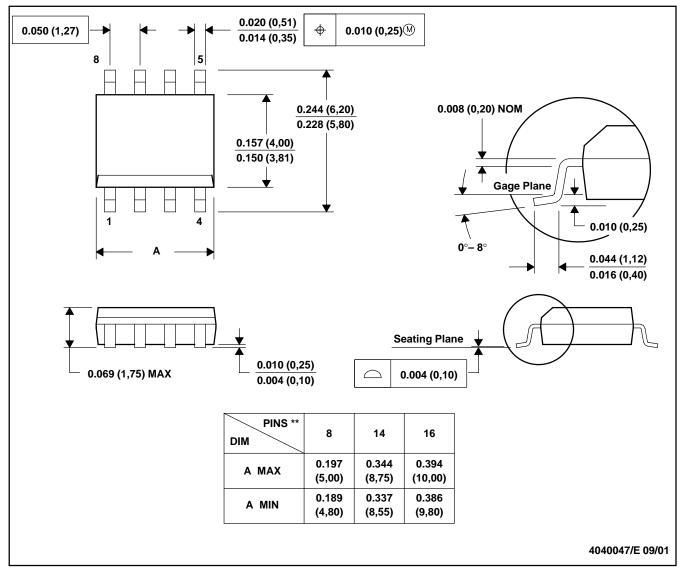
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

#### D (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **8 PINS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

#### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

### 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

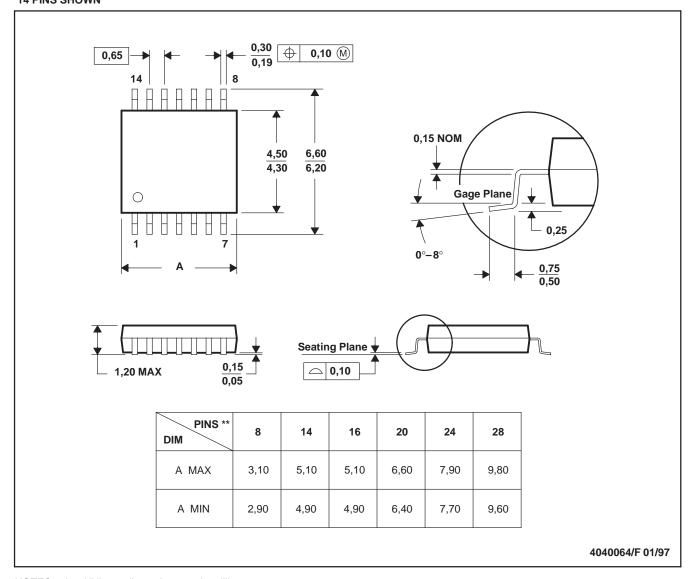
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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